

Amendments to the Specification:

Please replace paragraph [0066] with the following amended paragraph:

[0066] Table 1

		Relevant to claims for Epoxy (a)			
		Relevant to claims for Epoxy (b)			
		Example 1	Example 2	Example 3	Example 4
Epoxy resin	Epoxy (a)	Epoxy 1 (112.5 pbw)	Epoxy 2 (118.8 pbw)	Epoxy 3 (118.8 pbw)	Epoxy 4 (118.8 pbw)
	Epoxy (b)	Epoxy 7 (10 pbw)	Epoxy 8 (5 pbw)	Epoxy 9 (5 pbw)	Epoxy 8 (5 pbw)
		—	Epoxy 10 (3 pbw)	Epoxy 10 (5 pbw)	—
Curing agent		Curing agent 1 (39.5 pbw)	Curing agent 1 (44.0 pbw)	Curing agent 2 (34.2 pbw)	Curing agent 3 (29.2 pbw)
Curing accelerator		Accelerator 1 (0.13 pbw)	Accelerator 1 (0.13 pbw)	Accelerator 1 (0.13 pbw)	Accelerator 1 (0.13 pbw)
Organic solvent		Organic solvent 2 (18.6 pbw)	Organic solvent 2 (35 pbw)	Organic solvent 1 (8 pbw)	Organic solvent 2 (22.9 pbw)
				Organic solvent 2 (17.6 pbw)	Organic solvent 3 (22.9 pbw)
				Organic solvent 3 (25.6 pbw)	
Inorganic filler		—	—	—	—
Ratio of epoxy (a)+ epoxy (b) as a solid content per whole epoxy resin		100%	97%	95%	100%
Proportion of epoxy (a) as solid content per whole epoxy resin		90%	92%	90%	95%
Bromine content (%) in epoxy resin		23%	18.4%	18.1%	19%
Appearance of prepreg		Good	Good	Good	Good
Glass transition temperature		○(135□)	○(135□)	○(130□)	○(132□)
Fire retardancy		V-0	V-0	V-0	V-0
Moldability		○	○	□	○
Curing time for prepreg (second)	60 seconds	○	○	×	○
	80 seconds	○	○	○	○
	100 seconds	○	○	○	○
	140 seconds	○	○	○	○
	180 seconds	○	○	○	○
Coefficient of thermal expansion (α ₂₁)		65 ppm	65 ppm	65 ppm	65 ppm
Heat resistance in oven		270□	270□	265□	270□
Thermal decomposition temperature (weight loss by 5%)		355□	355□	350□	355□

		Relevant to claims for epoxy (a)			No-use relevant to claim
		Relevant to claims for epoxy (b)			
		Example 5	Example 6	Example 7	Comparative example 1
Epoxy resin	Epoxy (a)	Epoxy 5 (93.8 pbw)	Epoxy 2 (112.5 pbw)	Epoxy 5 (93.8 pbw)	Epoxy 3 (106 pbw)
	Epoxy (b)	Epoxy 7 (25 pbw)	Epoxy 7 (10 pbw)	Epoxy 7 (25 pbw)	—
		—	—	—	Epoxy 11 (15 pbw)

Curing agent	Curing agent 1 (38.6 pbw)	Curing agent 1 (39.5 pbw)	Curing agent 1 (38.6 pbw)	Curing agent 1 (44.8 pbw)
Curing accelerator	Accelerator 1 (0.13 pbw)	Accelerator 1 (0.13 pbw)	Accelerator 1 (0.13 pbw)	Accelerator 1 (0.13 pbw)
Organic solvent	Organic solvent 1 (8 pbw)	Organic solvent 2 (25 pbw)	Organic solvent 1 (8 pbw)	Organic solvent 1 (26 pbw)
	Organic solvent 2 (19 pbw)	Organic solvent 3 (25 pbw)	Organic solvent 2 (19 pbw)	Organic solvent 2 (10 pbw)
	Organic solvent 3 (19 pbw)		Organic solvent 3 (19 pbw)	
Inorganic filler	Inorganic filler 1 (19 pbw)	Inorganic filler 2 (63.8 pbw)	Inorganic filler 3 (19 pbw)	—
Ratio of epoxy (a) + epoxy (b) as a solid content per whole epoxy resin	100%	100%	100%	85%
Proportion of epoxy (a) as solid content per whole epoxy resin	75%	90%	75%	85%
Bromine content (%) in epoxy resin	27%	23%	27%	16.2
Appearance of prepreg	Good	Good	Good	Lack of resin uniformity
Glass transition temperature	○(135□)	○(134□)	×(105□)	○(143□)
Fire retardancy	V-0	V-0	V-0	V-0
Moldability	○	○	○	○
Curing time for prepreg (second)	60 seconds	○	○	○
	80 seconds	○	○	○
	100 seconds	○	○	○
	140 seconds	○	○	○
	180 seconds	○	○	○
Coefficient of thermal expansion (α ₂₁)	55 ppm	45 ppm	55 ppm	65 ppm
Heat resistance in oven	270□	270□	279□	265□
Thermal decomposition temperature (weight loss by 5%)	355□	355□	355□	350□

		Not relevant to epoxy (a)	Not relevant	
		Relevant to claim for epoxy (b)	No-use	Cured by DICY
		Comparative example 2	Comparative example 3	Comparative example 4
Epoxy resin	Epoxy (a)	Epoxy 6 (118.8 pbw)	Epoxy 6 (125 pbw)	Epoxy 6 (106 pbw)
	Epoxy (b)	Epoxy 8 (5 pbw)	—	—
		—	—	Epoxy 11 (15 pbw)
Curing agent		Curing agent 1 (41.7 pbw)	Curing agent 2 (21 pbw)	Curing agent 4 (2.5 pbw)
Curing accelerator		Accelerator 1 (0.13 pbw)	Accelerator 1 (0.13 pbw)	Accelerator 1 (0.05 pbw)

Organic solvent		Organic solvent 2 (33.3 pbw)	Organic solvent 1 (30 pbw)	Organic solvent 1 (13 pbw)
			Organic solvent 2 (10 pbw)	Organic solvent 2 (10.6 pbw)
				Organic solvent 4 (23.6 pbw)
Inorganic filler		—	—	—
Ratio of epoxy (a)+ epoxy (b) as a solid content per whole epoxy resin		100%	100%	—
Proportion of epoxy (a) as solid content per whole epoxy resin		95%	100%	—
Bromine content (%) in epoxy resin		19%	20%	—
Appearance of prepreg		Good	Some non-uniformity with resin	Good
Glass transition temperature		×(122□)	×(120□)	○(135□)
Fire retardancy		V-0	V-0	V-0
Moldability		○	□	○
Curing time for prepreg (second)	60 seconds	○	×	○
	80 seconds	○	○	○
	100 seconds	○	○	○
	140 seconds	○	○	○
	180 seconds	○	○	○
Coefficient of thermal expansion (α ₂₁)		65 ppm	65 ppm	65 ppm
Heat resistance in oven		265□	265□	240□
Thermal decomposition temperature (weight loss by 5%)		350□	350□	310□

Respectfully submitted,

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Date